

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application.

**Listing of Claims:**

Claims 1-70 (Canceled)

Claim 71 (Previously presented): A method of planarizing probes, wherein said probes are disposed to correspond to terminals of one or more devices to be tested and said probes are disposed on a plurality of substrates, said method comprising:

adjusting a planarity of contact portions of said probes to correspond to a planarity of said terminals, wherein said step of adjusting comprises:

adjusting a shape of a surface of a first of said substrates, wherein a first plurality of said probes is attached to said surface of said first substrate; and

adjusting a shape of a surface of a second of said substrates, wherein a second plurality of said probes is attached to said surface of said second substrate.

Claim 72 (Previously presented): The method of claim 71, wherein said step of adjusting a shape of a surface of said first substrate comprises selectively applying one of a push or a pull force to a first region of said first substrate.

Claim 73 (Previously presented): The method of claim 71, wherein said step of adjusting a shape of a surface of said first substrate further comprises:

applying a pull force to a first region of said first substrate, and

applying a push force to a second region of said first substrate.

Claim 74 (Previously presented): The method of claim 73, wherein:

said first region corresponds to a central region of said surface of said first substrate,  
said second region corresponds to a peripheral region of said surface of said first substrate.

Claim 75 (Previously presented): The method of claim 71, wherein said step of adjusting a shape of a surface of said first substrate further comprises applying a plurality of forces to a plurality of regions of said first substrate.

Claim 76 (Previously presented): The method of claim 71, wherein said step of adjusting a shape of a surface of a first of said substrates comprises adjusting said shape without contacting said one or more devices to be tested.

Claim 77 (Previously presented): The method of claim 76, wherein said step of adjusting a shape of a surface of a second of said substrates comprises adjusting said shape without contacting said one or more devices to be tested.

Claim 78 (Previously presented): The method of claim 71, wherein said step of adjusting a shape of a surface of a first of said substrates comprises activating an actuator configured to impart a selected one of a push force or a pull force to said first substrate.

Claim 79 (Previously presented): The method of claim 78, wherein said step of adjusting a shape of a surface of a second of said substrates comprises activating an actuator configured to impart a selected one of a push force or a pull force to said second substrate.

Claim 80 (Previously presented): The method of claim 71, wherein said step of adjusting a shape of a surface of a first of said substrates comprises selectively activating a plurality of first actuators, each said first actuator configured to impart a push or a pull force to a different region of said first substrate.

Claim 81 (Previously presented): The method of claim 80, wherein at least one of said first actuators is configured to impart a selected one of a push or a pull force to said first substrate, and at least another of said first actuators is configured to impart only a push force to said first substrate.

Claim 82 (Previously presented): The method of claim 81, wherein said step of adjusting a shape of a surface of a second of said substrates comprises selectively adjusting a plurality of second actuators, each said second actuator configured to impart a push or a pull force to a different region of said second substrate.

Claim 83 (Previously presented): The method of claim 82, wherein at least one of said second actuators is configured to impart a selected one of a push or a pull force to said second substrate, and at least another of said second actuators is configured to impart only a push force to said second substrate.

Claim 84 (Previously presented): The method of claim 80, wherein said step of adjusting a shape of a surface of a second of said substrates comprises selectively activating a plurality of second actuators, each said second actuator configured to impart a push or a pull force to a different region of said second substrate.

Claim 85 (Previously presented): The method of claim 71, wherein said first plurality of probes comprises a first array of probes.

Claim 86 (Previously presented): The method of claim 85, wherein said second plurality of probes comprises a second array of probes.

Claim 87 (Previously presented): The method of claim 71, wherein each said probe of said first plurality of probes is elongate and resilient, whereby each said probe of said first plurality of probes provides individual compliance with respect to said terminals of said device to be tested and said step of adjusting a shape of said first of said substrates provides global planarization of said first plurality of probes with respect to said terminals of said device to be tested.

Claim 88 (Previously presented): The method of claim 87, wherein each said probe of said second plurality of probes is elongate and resilient, whereby each said probe of said second plurality of probes provides individual compliance with respect to said terminals of said device to be tested and said step of adjusting a shape of said second of said substrates provides global planarization of said second plurality of probes with respect to said terminals of said device to be tested.

Claims 89-101 (Canceled)